



PC Board t=1.6mm
Component Side Shown

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		EC DIM	Ming-Wei 04/15/02	
△		Add Part No. Option	CHI 04/21/03	
△		MODIFY DRAWING	Syngs 7/24/03	
△		Add Part No. Option	Syngs 7/24/03	
△		MODIFY DRAWING	JULIEN 01/21/05	
△		Add Part No. Option	LUDWIN 03/02/05	
△		DEL P/N	WACON 4/19/05	
△		modify DIM	Jasper 7/27/06	

NOTES:

ELECTRICAL:

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 50 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

- HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

- STORAGE : -40°C TO +85°C.
 - OPERATION: -40°C TO +85°C.
- MATES WITH MODULAR PLUG CONFORMING TO
FCC PART 68, SUBPART F.

UL & CUL FILE NO. E163191

PART NUMBER: E5908-XXA1XX

- Gold Thickness:
1- 3u" 2- 6u" 3-15u"
4-30u" 5-50u"
- △ 1-W/O TABS
5-W/ TABS
- 4- W/ FRE LOGO
U- W/O FRE LOGO △
- T- Tin
V- Nickel
J- W/NICKEL PLATED WITH TINNED GROUNDING PEG

← MM (INCH) →		DFTO Ming-Wei	DATE 04/02/2002
TOLERANCES EXCEPT AS NOTED		CHKD	DATE
		MFO	DATE
DETACHED LISTS		APPVL oscar	DATE 07/27/06
MM		MATERIAL :	
.0 ±0.2	±	QT'Y :	
.00 ±0.15	±	FINISH :	
.000 ±0.075	±	SCALE : 1.5 : 1	
ANGLES ± 0.5		DO NOT SCALE DRAWING	
THIRD ANGLE PROJECTION		SHEET 1 OF 1	

FULL RISE ELECTRONIC CO., LTD

TITLE STAMPED PIN III
STACKED GANGED JACK, 2X2

DRAWING NO. GE593B54
/PART NO. SEE NOTE

SIZE A3
REV 8